AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) A method of metallizing a silicone rubber substrate, the method comprising the steps of:

(i) depositing a primer layer of aluminum on a surface of a silicone rubber substrate, wherein the silicone rubber substrate has a coefficient of linear thermal expansion of at least 2×10^{-4} °C^{-1}, and

(ii) depositing a layer of a ductile metal on the primer layer of aluminum, wherein the ductile metal is selected from gold, platinum, palladium, copper, silver, aluminum, and indium.

2. (Currently amended) The method according to claim 1, wherein the silicone rubber substrate is prepared by curing a curable silicone composition selected from a hydrosilylation-curable silicone composition, a peroxide curable silicone composition, a condensation-curable silicone composition, an epoxy-curable silicone composition[[;]], an ultraviolet radiation-curable silicone composition, and a high-energy radiation-curable silicone composition.

3. (Canceled). The method according to claim 2, wherein the curable silicone composition further comprises an inorganic filler.

4. (Canceled) The method according to claims 1, 2, or 3, wherein the primer layer of aluminum has a thickness of from 1 to 200 nm.

5. (Canceled) The method according to claims 1, 2, 3, or 4, wherein the layer of a ductile metal has a thickness of from 20 to 500 nm.

6. (Currently amended) The method according to claim[[s]] 1, ~~2, 3, 4, or 5,~~ wherein the ductile metal is gold or platinum.

7. (New) The method according to claim 2, wherein the curable silicone composition is a hydrosilylation-curable silicone composition comprising (i) an organopolysiloxane containing an average of at least two silicon-bonded alkenyl groups per molecule, (ii) an organohydrogensiloxane containing an average of at least two silicon-bonded hydrogen atoms per molecule in an amount sufficient to cure the composition, and (iii) a hydrosilylation catalyst.

8. (New) The method according to claim 2, wherein the curable silicone composition is a condensation-curable silicone composition comprising (i) an organopolysiloxane containing an average of at least two hydroxy groups per molecule, and (ii) a tri- or tetra-functional silane containing hydrolysable Si-O or Si-N bonds.

9. (New) The method according to claim 8, wherein the silane contains silicon-bonded alkoxy groups.

10. (New) The method according to claim 8, wherein the condensation-curable silicone composition further comprises a condensation catalyst.

11. (New) The method according to claim 2, wherein the curable silicone composition is a peroxide-curable silicone composition comprising an organopolysiloxane and an organic peroxide.

12. (New) The method according to claim 2, wherein the curable silicone composition further comprises an inorganic filler.

13. (New) The method according to claim 1, wherein the primer layer of aluminum has a thickness of from 1 to 200 nm.

14. (New) The method according to claim 13, wherein the primer layer of aluminum has a thickness of from 1 to 35 nm.

15. (New) The method according to claim 1, wherein the layer of a ductile metal has a thickness of from 20 to 500 nm.

16. (New) The method according to claim 15, wherein the layer of a ductile metal has a thickness of from 50 to 500 nm.